

Title (en)
BUFFER DEVICE

Title (de)
PUFFERVORRICHTUNG

Title (fr)
DISPOSITIF TAMPON

Publication
EP 1080290 A1 20010307 (DE)

Application
EP 00907402 A 20000314

Priority
• CH 0000145 W 20000314
• CH 48199 A 19990316

Abstract (en)
[origin: WO0055460A1] The buffer device (10) has a body (11) which can be fitted in a rail (4), a damping element (12) for cushioning, and a retaining spring (13) for retaining a running mechanism (6) which is guided in the rail (4) and is provided for carrying and guiding sliding wing elements (2). The at least approximately U-profile-shaped wing element of the buffer device (10), whose body is punched and bent from a metal element, has a first and a second wing (14; 18), these wings being connected to each other by a central piece (20) whose tongue-shaped extension forms the retaining spring (13) serving to retain the running mechanism (6). The end pieces (17, 19, 26; 17*, 19*) of the wings (14; 18) are configured in such a manner that they are suitable for retaining the damping element (12). The buffer device (10) can be manufactured cost-effectively from a single metal plate and can be completed by a damping element (12). Since the retaining spring (13) is a component part of the body (11) of the buffer device (10), the device is highly stable.

IPC 1-7
E05D 13/00; **E05F 5/00**

IPC 8 full level
E05C 17/60 (2006.01); **E05D 13/00** (2006.01); **E05F 5/00** (2006.01); **E05F 5/02** (2006.01); **F16F 7/00** (2006.01)

CPC (source: EP US)
E05D 13/04 (2013.01 - EP US); **E05F 5/00** (2013.01 - EP); **E05F 5/003** (2013.01 - EP US); **E05Y 2201/212** (2013.01 - EP US); **E05Y 2201/218** (2013.01 - EP US); **E05Y 2201/264** (2013.01 - EP US); **E05Y 2201/48** (2013.01 - EP US); **E05Y 2201/492** (2013.01 - EP US); **E05Y 2900/132** (2013.01 - EP US)

Cited by
BE1020253A5; EP2937502A1

Designated contracting state (EPC)
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE

DOCDB simple family (publication)
WO 0055460 A1 20000921; AR 022924 A1 20020904; AT E261538 T1 20040315; AU 2901200 A 20001004; AU 757341 B2 20030220; BR 0005390 A 20010109; CA 2331459 A1 20000921; CA 2331459 C 20080812; CN 1144926 C 20040407; CN 1300339 A 20010620; CZ 20004227 A3 20011114; DE 50005580 D1 20040415; EE 04027 B1 20030415; EE 200000623 A 20020215; EP 1080290 A1 20010307; EP 1080290 B1 20040310; ES 2215611 T3 20041016; GC 0000332 A 20070331; HK 1035567 A1 20011130; HU 224563 B1 20051028; HU P0101880 A2 20011028; HU P0101880 A3 20020228; IL 137708 A0 20011031; IL 137708 A 20031031; JO 2224 B1 20041007; JP 2002539345 A 20021119; JP 4468591 B2 20100526; NO 20005801 D0 20001116; NO 20005801 L 20001116; NO 319852 B1 20050926; NZ 506268 A 20020628; RU 2222678 C2 20040127; SK 16902000 A3 20010710; SK 286002 B6 20080107; TR 200003367 T1 20010723; TW M245289 U 20041001; US 6438795 B1 20020827; ZA 200001027 B 20001016

DOCDB simple family (application)
CH 0000145 W 20000314; AR P000101115 A 20000314; AT 00907402 T 20000314; AU 2901200 A 20000314; BR 0005390 A 20000314; CA 2331459 A 20000314; CN 00800337 A 20000314; CZ 20004227 A 20000314; DE 50005580 T 20000314; EE P200000623 A 20000314; EP 00907402 A 20000314; ES 00907402 T 20000314; GC P2000557 A 20000307; HK 01106275 A 20010905; HU P0101880 A 20000314; IL 13770800 A 20000314; IL 13770899 A 19990316; JO P20000018 A 20000308; JP 2000605067 A 20000314; NO 20005801 A 20001116; NZ 50626800 A 20000314; RU 2000131602 A 20000314; SK 16902000 A 20000314; TR 200003367 T 20000314; TW 92213023 U 20000313; US 67317100 A 20001012; ZA 200001027 A 20000301